

# SOD119AB

hermetically sealed glass package; axial leaded; 2 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	A (axial)
<b>Package type descriptive code</b>	GALF2
<b>Package type industry code</b>	GALF2
<b>Package style descriptive code</b>	LALF (glass axial (leaded) long form)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	L (glass)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	4-12-1998

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	[tbd]	-	5.5	5.5	mm
$\Phi$ D	package diameter	[tbd]	-	2.5	2.5	mm
n <sub>2</sub>	actual quantity of termination	-	-	2	-	



## 2. Package outline

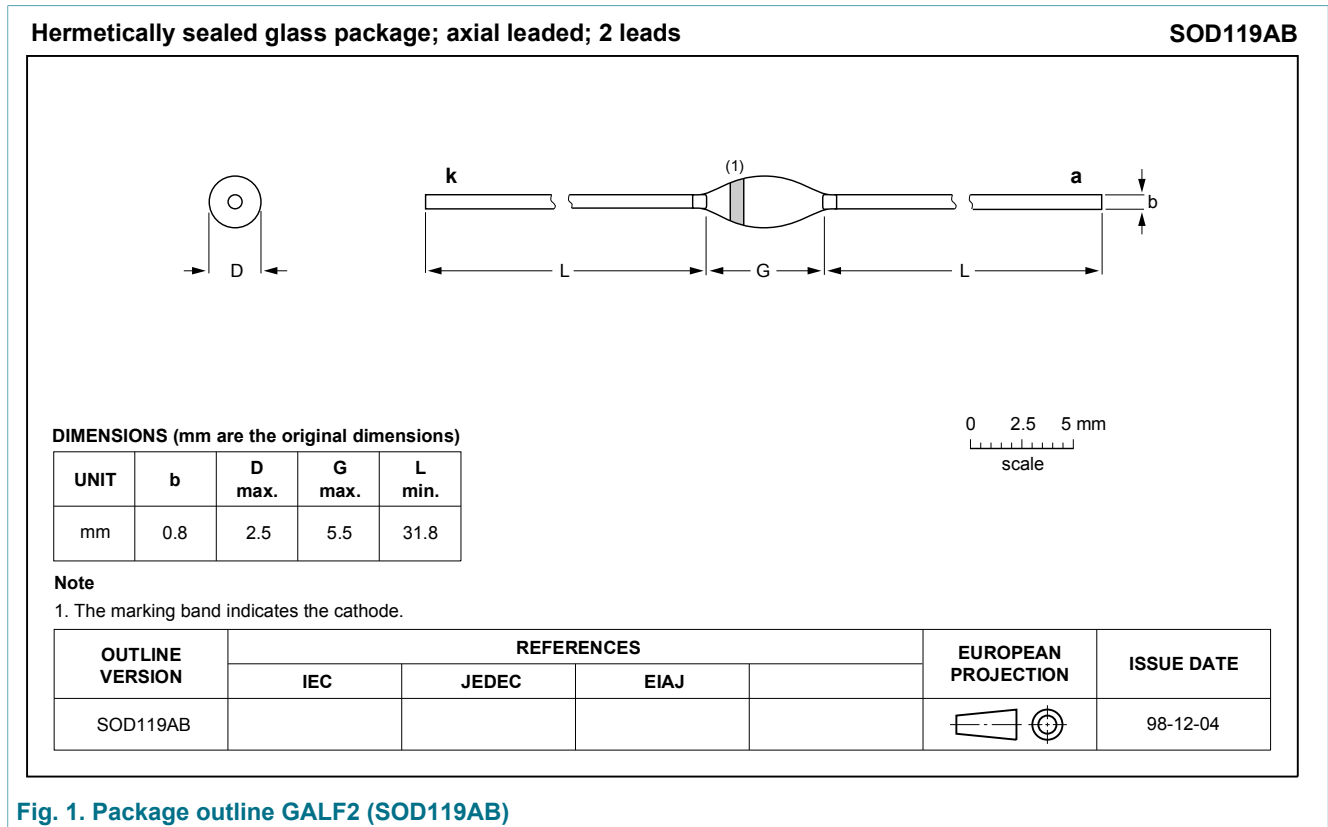


Fig. 1. Package outline GALF2 (SOD119AB)

### 3. Legal information

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